



[10191/1629]

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s) : LAERMER et al. Confirmation No.: 5642
Serial No. : 09/720,761
Filed : March 26, 2001
For : METHOD OF PLASMA ETCHING OF SILICON
Examiner : K. Chen
Art Unit : 1765
Customer No. : 26646

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OK to enter

AMENDMENT

File 9/3/06

SIR:

As a supplemental response to the final Office Action dated February 22, 2006, and as a response to the Advisory Action mailed on June 7, 2006, please amend the above-captioned application as follows.

Amendments to the Specification do not appear in this paper.

Amendments to the Claims are found in the listing of the claims which begins on page 2 of this paper.

Amendments to the Drawings do not appear in this paper

Remarks begin on page 4 of this paper.

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